Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model [List multiple models if applicable.]
HP Pro SFF 400 G9 Desktop PC/HSC-F003SF

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP Inc. products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking or identification of location of parts or components requiring selective treatment, please contact HP's Sustainability Contact.

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment. An "X" in the list of components and parts indicates the product contains the component or part requiring selective treatment

Item Description	Components and parts requiring selective treatments	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA) with a surface greater than 10 sq cm	[x] Main board (MB) PCB [x] Solid state drive (SSD) PCB [x] Hard disk drive (HDD) PCB [x] Memory PCB [x] Internal power supply (IPS) PCB [x] External Keyboard (KB) [x] External Mouse [x] Others: Graphic Card PCB	9
Batteries, excluding Li-Ion batteries. This includes standard alkaline, coin or button style batteries	RTC coin battery	1
Li-Ion batteries. Includes all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, etc.)	Battery(ies) are attached to the product by: [ ] screws [ ] snaps [ ] adhesive [ ] other. Explain _____	0
Mercury-containing components. For example, mercury in lamps, display backlights, scanner lamps, switches, batteries		0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm. Includes background illuminated displays with gas discharge lamps	[ ] Panel LCD	0
Cathode Ray Tubes (CRT)		0

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Item Description	Components and parts requiring selective treatments	Quantity of items included in product
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	[x] Power Supply capacitor(s) or condenser(s)	1
External electrical cables and cords	[x] AC power cord [ ] Audio, video or data cables [ ] Other:	1
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants (not including external electrical cables and cords, PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner. Include the cartridges, print heads, tubes, vent chambers, and service stations.		0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0
Components containing chlorofluorocarbons (CFC), hydrochlorofluorocarbons (HCFC) or hydrofluorocarbons (HFC), hydrocarbons (HC)		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Hexagon Screw Driver	T-15
Electric Iron	QUICK 310
Crisscross Screw Driver	PH1

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. Use T-15 screwdriver to release thumb screw.
2. Remove access pane

EL-MF877-00
Template Revision D

3. Disconnect ODD SATA cable and power cable
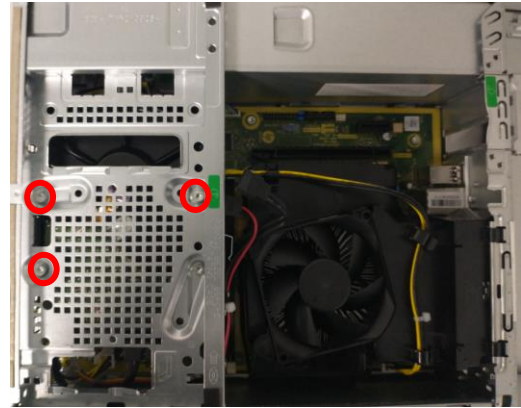
4. Remove ODD from cage

5. Remove the front bezel

6. Rotate and open drive cage

7. Disconnect HDD SATA cable and power cable

8. Loose the Screw and remove HDD

9. Remove HDD from Chassis, The PCA of HDD as below:

10. Remove fan duct latch

11. Remove fan duct

12. Remove CPU cooler

13. Rotate the handle and open it up

14. Remove the CPU from the board

15. Open the GFX Lock

16. Unlock the slot latch and remove Graphic from MB

17. Remove the Graphic card From MB and Show Graphic card PCA as below

18. Remove Memory from MB

19. Remove Memory from MB and show Memory PCA as below

20. Release the screw and remove WLAN from MB

21. Release the screw and remove SSD from MB

22. Remove SSD from MB and show the SSD PCA.

23. Disconnect speaker power cable from MB

24. Remove Speaker BOX from chassis

25. Use T-15 screwdriver to release the screws of MB

26. Remove MB from chassis

27. Use T-15 screwdriver to release the screws of PSU

28. Press the PSU's latch on chassis

29. Remove the PSU from chassis

30. Remove four screws covered

31. Remove the screw and open case

32. Loose screws and remove PCB from case

33. Remove Ele-Cap from PCBA

34. Show Ele-Cap on PCBA (C1)

NOTE - For disassembly instructions of the external power supply (EPS), external keyboard (KB) external mouse and external cables and cords, refer to the links below:

Generic Keyboard

Generic Mouse

Generic cables and cord

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Step1 Use T-15 screwdriver to release thumb screw.	Step 2 Remove access panel.
Release the access panel	
Step 3 Disconnect ODD SATA cable and power cable	Step 4 Remove ODD
Step 5 Release the front bezel	Step6 Rotate and open drive cage

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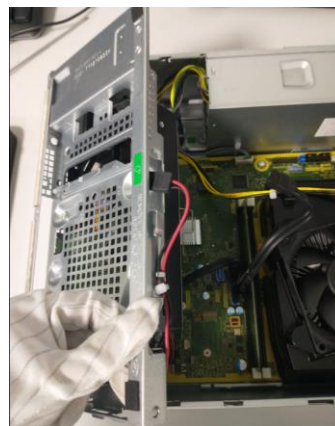
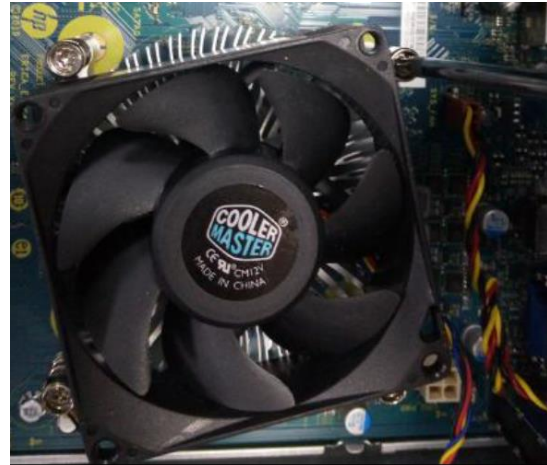| Step7 Disconnect HDD SATA cable and power cable	Step 8 Loose the Screw and remove HDD
Step9 Remove HDD from Chassis, The PCA of HDD as below:	Step10: Remove fan duct latch

HPI instructions for this template are available at EL-MF877-01
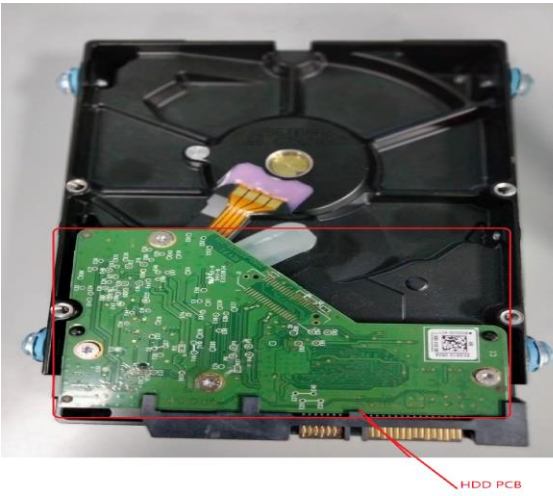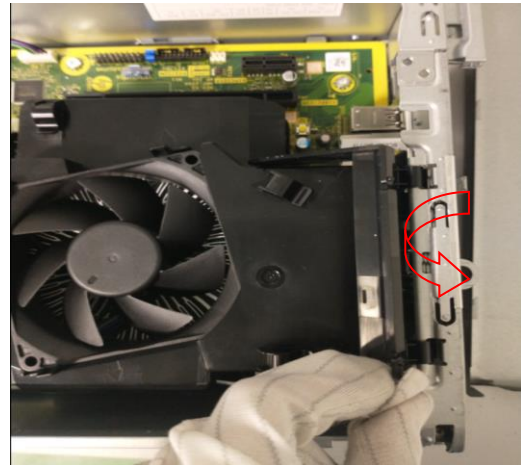
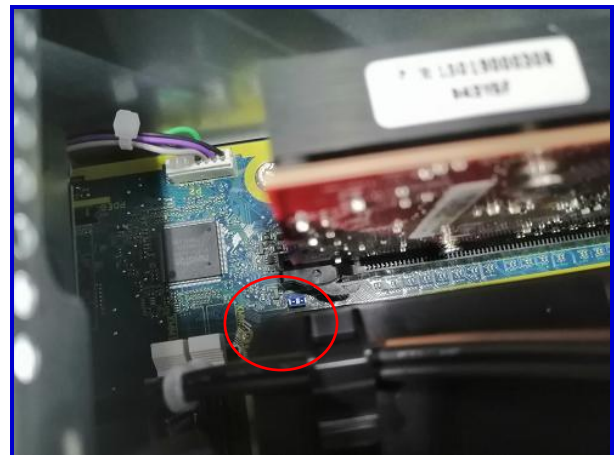| Step 11 Remove fan duct	Step 12 Remove CPU cooler
Step 13 Rotate the handle and open it up	Step 14 Remove the CPU from the board.
Step15 Open the GFX Lock	Step 16 Unlock the slot latch and remove Graphic from MB

HPI instructions for this template are available at EL-MF877-01
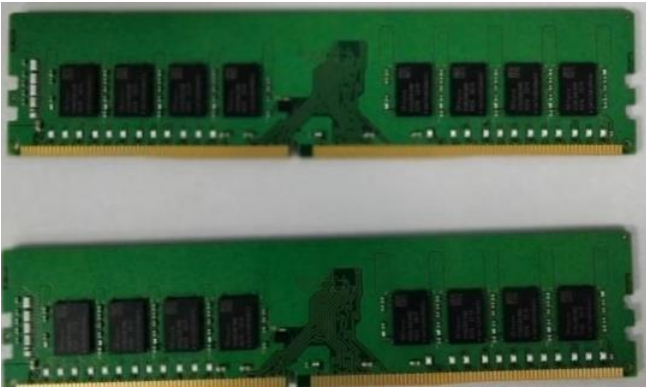
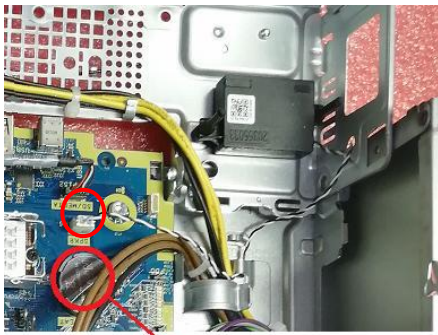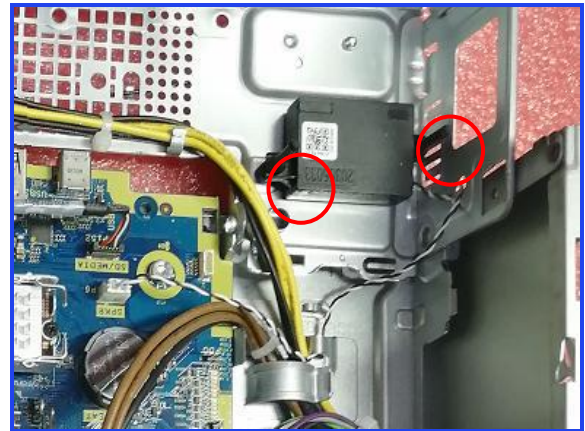|	
.Step 17 Remove the Graphic card From MB and Show Graphic card PCA as below: 	Step18 Remove Memory from MB
Step19 Remove Memory from MB and show Memory PCA as below: 	Step 20 Release the screw and remove WLAN from MB
Step21 Release the screw and remove SSD from MB 	Step22 Remove SSD from MB and show the SSD PCA.
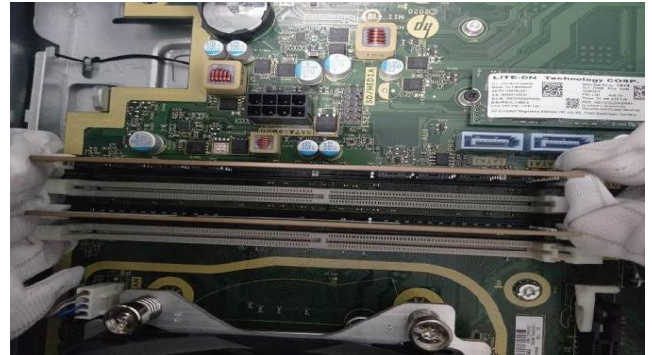
Template Revision D

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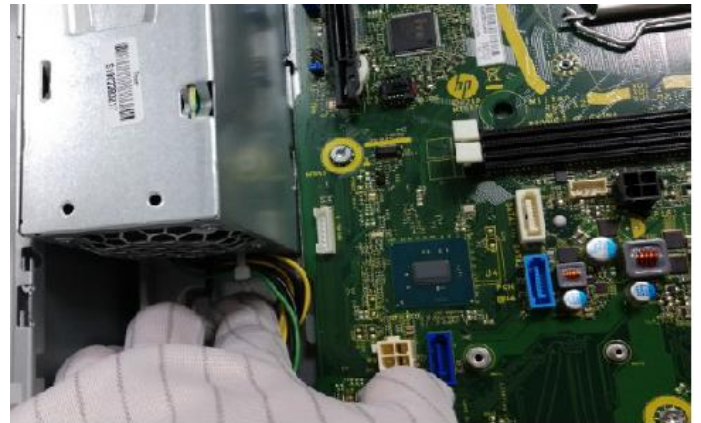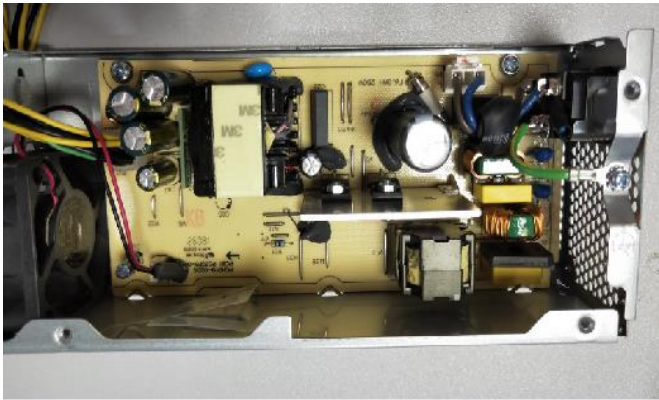| Step 23 Disconnect speaker power cable from MB	Step 24 Remove Speaker BOX from chassis
Coin battery	
Step 25 Use T-15 screwdriver to release the screws of MB	Step 26 Remove MB from chassis
Step 27 Use T-15 screwdriver to release the screws of PSU	Step 28 Press the PSU's latch on chassis

Template Revision D

last updated 3-March-2022

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Step 29 Remove the PSU from chassis	Step 30 Remove four screws covered
Step 31 Remove the screw and open case	Step 32 Loose screws and remove PCB from case
Step 33 Remove Ele-Cap from PCBA	Step 34 Show Ele-Cap on PCBA (C1)

HPI instructions for this template are available at EL-MF877-01